EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	145	("204" "205").clas. and frame and base and spring with (electrical electrode) and seal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/05 16:21
S2	232	("204" "205").clas. and frame and base and spring with (electrical electrode)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/05 16:21
S4	1	("204" "205").clas. and frame and base and spring with (electrical electrode) and seal and thrust adj plate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/05 16:23
S7	40	("204" "205").clas. and spring with (electrical electrode) and seal\$4 and ((thrust adj plate) (backing adj plate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/05 16:24
S6	2	("204" "205").clas. and spring with (electrical electrode) and seal\$4 and thrust adj plate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/05 16:24
S5	2	("204" "205").clas. and spring with (electrical electrode) and seal and thrust adj plate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/05 16:24
S8	477	("204" "205").clas. and frame and base and spring and (semiconductor wafer microelectronic microfeature electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 13:54
S1	852	("204" "205").clas. and frame and base and spring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 13:54
S9	299	("204" "205").clas. and frame and base and spring and (semiconductor wafer microelectronic microfeature electronic) and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 13:55

EAST Search History

S13	4	("5227041".pn.) "6139712".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:20
S12	5	("5227041".pn.) "9925905"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:20
S11	4	("6540899" "6399479").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:20
S10	198	("204" "205").clas. and frame and base and spring and (semiconductor wafer microelectronic microfeature electronic) and copper and anode and cathode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:22
S14	3	("204" "205").clas. and (semiconductor wafer microelectronic microfeature electronic) and copper and anode and cathode and distribut\$ with force with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:25
S15	12	("204" "205").clas. and anode and cathode and distribut\$ with force with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:30
S16	1	(204/297.09 204/297.1).ccls. and distribut\$ with force with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:33
S18	2	"20050092614".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:46
S17	280	(204/297.09 204/297.1).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/08 14:46
S19	4	("6495007" "6749728").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/09 13:26

EAST Search History

S20	4 jorne.in. and electroplating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/10 10:40
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